

IN THE CLAIMS:

Please **amend** claims 1, 5 and 7, as follows:

1. (Thrice Amended) A semiconductor device including a semiconductor chip having a principal surface and a back surface, opposite to said principal surface, disposed in a device hole provided in a tape carrier including a base layer and a lead portion bonded thereto with one end of a lead of said lead portion being electrically connected to an external terminal of said semiconductor chip, said semiconductor device being disposed in the device hole such that the principal surface thereof is facing in the same direction as the side of said base layer to which said lead portion is bonded, characterized in that said semiconductor chip has a reduced thickness defined by spin-etching of said back surface to effect a thinning of said semiconductor chip to a thickness less than that of said tape carrier, and that said thinned semiconductor chip is sealed, covering both the principal and back surfaces thereof, by a seal resin material to achieve a thickness at the resin sealed location of said device equal to the combined thickness of the base layer and lead portion of said tape carrier.

5. (Twice Amended) The semiconductor device as recited in claim 1, characterized in that an injection port for use in seal resin injection is provided at part of said tape carrier to effect coupling of said device hole to a gate of a metal mold structure used during formation of said seal resin.

7. (Twice Amended) The semiconductor device as recited in claim 5, characterized in that an electroplated metal layer is formed at part of a surface of said tape carrier in close proximity to said injection port for seal resin injection, the part being brought into contact with the seal resin during formation of said resin seal.